

DLA Land and Maritime - VQ
Supplemental Information Sheet for Electronic QML-38534

Date: 8/14/2013

Specification Details:

Specification: MIL-PRF-38534
Title: Hybrid Microcircuits
Federal Supply Class (FSC): 5962
Conventional: No
Specification contains quality assurance program: Yes
MIL-STD-790 Established Reliability & High Reliability: No
MIL-STD-690 Failure Rate Sampling Plans & Procedures: No
Weibull Graded: No
Specification contains space level reliability requirements: Yes
Specification allows test optimization: Yes

Contact Information:

Office of Primary Involvement: Hybrid Devices Branch, DLA Land and Maritime - VQH
Primary Qualifying Activity Contact: 614-692-0596, e-mail: vqh.rb@dla.mil
Secondary Qualifying Activity Contact: 614-692-0582, e-mail: vqh.esr@dla.mil

Notes:

In order for a manufacturer to have test data considered for qualification, the manufacturer must perform all required qualification tests; produce the qualification sample with DLA Land and Maritime-VQ certified materials and manufacturing construction techniques; and comply with the requirements specified in MIL-PRF-38534.

Custom hybrid microcircuit materials and manufacturing construction techniques in this listing applies only to products produced on the MIL-PRF-38534 certified line(s) at the plant(s) specified in this listing.

Custom hybrid microcircuits manufactured, assembled, and tested in accordance with MIL-PRF-38534 shall bear the "certification mark" for SMD controlled hybrid Microcircuits, or the "compliant hybrid" certification mark for non-SMD controlled hybrid microcircuits as follows:

SMD product, for all classes, shall have the certification mark "QML" or "Q" for small devices.
Non-SMD product dated after MIL-PRF-38534D, for Class K shall have the certification mark "CK."
Non-SMD product dated after MIL-PRF-38534D, for Class H shall have the certification mark "CH."
Non-SMD product dated after MIL-PRF-38534D, for Class G shall have the certification mark "CG."
Non-SMD product dated after MIL-PRF-38534D, for Class E shall have the certification mark "CE."
Non-SMD product dated after MIL-PRF-38534D, for Class D shall have the certification mark "CD."
Non-SMD dated prior to MIL-PRF-38534D, for all classes, shall have the certification mark "CH" or "C" for small devices.

These certification marks or the abbreviations "Q" or "C" shall not be used on product that does not meet all requirements of MIL-PRF-38534 except as allowed in 3.7.5 of MIL-PRF-38534.

Products manufactured, assembled, and tested for Class K, Class H, Class G, Class E, or Class D, with all the provisions of MIL-PRF-38534, and with DLA Land and Maritime-VQ qualified materials and manufacturing construction techniques, can be represented as being compliant to the appropriate product assurance levels as listed herein. The information contained in this listing reflects the general material and manufacturing techniques of the particular test sample(s). In order to protect the manufacturers' proprietary processes and materials, only the generic process and material are listed. The user must contact the manufacturer for any detail information on specific materials (i.e., such as epoxy, getter, solder-type), or process details. Processes and materials, not listed, may be considered qualified by similarity to those demonstrated for the qualification (e.g., different wire, package, or die sizes). See Appendix E of MIL-PRF-38534, Class I, major changes paragraph, for a baseline of qualification limits.

Any product represented as being compliant to MIL-PRF-38534 must be built using qualified processes and materials. The user shall be responsible for determining if the qualification baseline for a given class level is adequate to demonstrate capability for the intended application.

To obtain MIL-PRF-38534 qualified hybrid microcircuits, the user should specify in the procurement document that the product be manufactured to MIL-PRF-38534, and be comprised of materials and manufacturing construction techniques listed herein. Acquisition requirements are contained in paragraph 6.2 of MIL-PRF-38534. Microcircuit devices represented as being built, tested and shipped under the QML provision of MIL-PRF-38534 must be built using qualified manufacturing materials and construction in this listing.

Contractor acquiring activities, military program offices, and other government representatives can determine if hybrid microcircuits meet the requirements of MIL-PRF-38534 by:

- a. For SMD controlled product: Product listed in the product eligibility section herein and marked with "QML" or "Q".
- b. For non-SMD controlled Product: The part will not be listed herein. However, the part will be marked with "C" plus the Class Level designator".

WARNING! If products were not purchased to, and identified as MIL-PRF-38534 compliant, do not assume they have been manufactured on the DLA Land and Maritime-VQ certified line, with qualified materials and processes, or that all other MIL-PRF-38534 requirements were performed. To determine whether new SMD controlled products are in accordance with MIL-PRF-38534, or to verify any new process/material qualifications, you may call the qualifying activity (DLA Land and Maritime-VQ).

DLA Land and Maritime-VQ ISO Registrations are also listed herein. However, QML listed manufacturers may have ISO registrations from other registrars.

1/ This listing can be expanded provided appropriate qualification testing is performed and passed. Therefore the manufacturer may accept an order for compliant product not covered by his listing, but shall not ship the compliant product until the testing has been successfully completed.

2/ Package seal perimeter is listed by largest perimeter successfully tested in inches.

3/ Package lead counts are listed by maximum number of leads covered by qualification.

4/ Caution. Do not use this number for item acquisition. Item acquired to this number may not satisfy the performance requirements of the listed SMD.

5/ Inactive for new design, no longer available from manufacturer.

6/ Class E devices are devices which meet all of the requirements of one of the other classes (K, H, or G), with some exceptions taken. Therefore any manufacturer qualified to G, H or K is eligible to produce and mark product as compliant to class E.

Part Configuration:

Standardized Microcircuit Drawing (SMD)

5962	99616	01	H	X	A
Federal Stock Class	SMD Number	Device Number	Class	Package Type	Lead Finish

Process/Material Listings:

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Aeroflex Microelectronic Solutions (CAGE Code: 88379)

35 South Service Road, Plainview, NY 11803-4193, US

Company Contact: Mr. Joe Mazzotta, Phone: 516-752-2359, Fax: 516-694-6715, E-mail: Joe.Mazzotta@aeroflex.com

DSCC Contact: Ms. Jacqueline Cunningham, Phone: 614-692-0584, Fax: 614-692-6942, E-mail: vqh.jc@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Linear, Analog, Digital, Power, Voltage Regulator

Aeroflex Microelectronic Solutions

Qualification Letters: EQ(EQC-90-616), EQ(EQC-91-896), EQ(EQC-92-001), EQ(EQC-93-019), EQ(EQC-94-032), ELS(ELSH-94-0342), ELS(ELSH-95-0042), ELS(ELSH-95-0395), ELS(ELSH-96-0130), ELS(ELSH-96-176), VQ(VQH-98-0001), VQ(VQH-99-0028), VQ(VQH-01-0070), VQ(VQH-01-0081), VQH-02-000431, VQ(VQH-02-001027), VQ(VQH-04-5086), VQ(VQH-04-005472), VQ(VQH-04-006026), VQ(VQH-04-006367), VQ(VQH-05-008607), VQ(VQH-05-009404), VQ(VQH-06-010542), VQ(VQH-07-012806), VQ(VQH-11-022595), VQ(VQH-13-025566)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: QAP21-225, QAP21-240

Substrate Fabrication: Thick Film on Alumina, 6 Conductor Level(s), Resistors; Thick Film on Beryllia, 1 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: QAP21-241, QAP21-337

Substrate Attach: Solder, Nonconductive Epoxy, Conductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Daughter Board, Transformers, Optocoupler Assembly

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Seam Weld, 7.94 Inch Seal Perimeter, 90 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Seam Weld, 3.72 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 7.01 Inch Seal Perimeter, 88 Leads, Gold/Solder Lead Finish; Metal Package, Platform, Projection Weld, 3.93 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Ceramic Co-fire Package, Axial Leads, Seam Weld, 7.66 Inch Seal Perimeter, 90 Leads, Gold Lead Finish; Metal Package, Flatpack, Seam Weld, 5.00 Inch Seal Perimeter, 96 Leads, Gold Lead Finish; Ceramic Package, Leadless Chip Carrier, Seam Weld, 1.39 Inch Seal Perimeter, 5 Leads, Gold Lead Finish; Ceramic Co-fire Package, Axial Leads, Solder Seal, 1.43 Inch Seal Perimeter, 16 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Aeroflex Microelectronic Solutions (CAGE Code: 88379)

35 South Service Road, Plainview, NY 11803-4193, US

Company Contact: Mr. Joe Mazzotta, Phone: 516-752-2359, Fax: 516-694-6715, E-mail: Joe.Mazzotta@aeroflex.com

DSCC Contact: Ms. Jacqueline Cunningham, Phone: 614-692-0584, Fax: 614-692-6942, E-mail: vqh.jc@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Linear, Analog, Digital, Power, Voltage Regulator

Cirtek Electronics Corp. Philippines Plant

Qualification Letters: VQ(VQH-03-003903), VQ(VQH-03-004625)

Class Level Information: See Note 6/

Class H

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: N/A

Assembly Information: See Note 1/

Assembly Flows: QAP21-241

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Tabs, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: N/A

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Analog Devices Incorporated (CAGE Code: 34031)

Assembled Products Division, 7910 Triad Center Drive, Greensboro, NC 27409-9605, US

Company Contact: Ms. Elaine Trotter, Phone: 336-605-4234, Fax: 336-605-4347, E-mail: elaine.trotter@analog.com

DSCC Contact: Mr. Joseph Buben II, Phone: 614-692-0592, Fax: 614-692-6942, E-mail: vqh.jbu@dla.mil

Quality Management (QM) Program: TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: AD/DA Converters, Buffer, Op-Amp, Track and Hold, Voltage Reference, Signal Processor, Data Acquisition Systems, DC/DC Converters

Sub: RF2M Microelectronics Ltd. (Cage: U4388)

Qualification Letters: VQ(VQH-04-006510), VQ(VQH-04-007022), VQ(VQH-04-007023), VQ(VQH-05-008727), VQ(VQH-06-010144), VQ(VQH-09-017847)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Ceramic Co-fire; Thick Film, 4 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: FCES 6301:15

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors, Ceramic Tabs, Transformers

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Co-fire Package, Dual-in-line, Seam Weld, 2.53 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Seam Weld, 5.38 Inch Seal Perimeter, 32 Leads, Gold Lead Finish; Ceramic Package, Quad Flat Pack, Seam Weld, 3.48 Inch Seal Perimeter, 68 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Apex Microtechnology Incorporated (CAGE Code: 60024)

5980 North Shannon Road, Tucson, AZ 85741-5230, US

Company Contact: Mr. Mark Collingham, Phone: 520-690-8695, Fax: 520-888-3329, E-mail: mark.collingham@apexanalog.com

DSCC Contact: Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: Yes

Technologies: Power Op-Amp

Qualification Letters: EQ(EQC-91-347), EQ(EQC-92-410), EQ(EQC-92-416), EQ(EQC-93-028), EQ(EQC-93-595), ELS(ELSH-94-0354), ELS(ELSH-95-0070)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: Flow 01

Substrate Fabrication: Thick Film on Beryllia, 1 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: Flow 10, Flow 99

Substrate Attach: Solder

Element Attach: Conductive Epoxy, Solder

Add-on Elements: Unpackaged Die, Chip Capacitors

Wire Bonding: Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, TO can, Projection Weld, 2.67 Inch Seal Perimeter, 8 Leads, Gold/Solder Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

API Technologies RF/Microwave & Microelectronics (CAGE Code: 27851)

400 Nickerson Road, Marlborough, MA 01752, US

Company Contact: Mr. Gregory Madden, Phone: 508-251-6429, Fax: , E-mail: Gregory.Madden@apitech.com

DSCC Contact: Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 2

Approved ISO 9000 System: No

Technologies: Low Power, Analog, Voltage Reference, Direct Bond Copper Hybrid

Qualification Letters: EQ(EQC-89-421), ELS(ELSH-94-0252), ELS(ELSH-94-0253), ELS(ELSH-94-0254), ELS(ELSH-95-0183), VQ(VQH-98-0177), VQ(VQH-98-0232), VQ(VQH-99-0176), VQ(VQH-99-0204), VQ(VQH-01-0102), VQ(VQH-01-0104), VQ(VQH-03-004619), VQ(VQH-04-004898), VQ(VQH-04-005172), VQ(VQH-06-011842), VQ(VQH-07-013689), VQ(VQH-08-014380)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 52-0059

Substrate Fabrication: Thin Film on Alumina, 2 Conductor Level(s), Resistors; Thin Film on Alumina, 1 Conductor Level(s); Thin Film on Beryllia, 1 Conductor Level(s); Purchased Direct Bonded Copper on Alumina Nitride, 2 Conductor Level(s); Purchased Thick Film on Alumina, 5 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: 12-0902

Substrate Attach: Nonconductive Epoxy, Solder

Element Attach: Conductive Epoxy, Solder, Nonconductive Epoxy, Eutectic

Add-on Elements: Unpackaged Die, Chip Resistors, Chip Capacitors

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Peripheral Leads, Seam Weld, 3.58 Inch Seal Perimeter, 16 Leads, Gold Lead Finish, Getter Qualified; Metal Package, TO can, Projection Weld, 1.65 Inch Seal Perimeter, 12 Leads, Gold Lead Finish, Getter Qualified; Metal Package, TO can, Projection Weld, 6.00 Inch Seal Perimeter, 12 Leads, Nickel Lead Finish, Getter Qualified; Ceramic Package, Dual-in-line, Seam Weld, 2.57 Inch Seal Perimeter, 14 Leads, Gold Lead Finish; Ceramic Package, Leadless Chip Carrier, Seam Weld, 1.62 Inch Seal Perimeter, 28 Leads, Solder Lead Finish; Ceramic Package, Single-in-line, Seam Weld, 2.90 Inch Seal Perimeter, 10 Leads, Gold Lead Finish; Copper Package, Single-in-line, Seam Weld, 4.90 Inch Seal Perimeter, 17 Leads, Nickel Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

API Technologies RF/Microwave & Microelectronics (CAGE Code: 50507)

400 Nickerson Road, Marlborough, MA 01752, US

Company Contact: Mr. Gregory Madden, Phone: 508-251-6429, Fax: , E-mail: Gregory.Madden@apitech.com

DSCC Contact: Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Data Converters, Track and Hold Amp

Qualification Letters: EQ(EQM-88-0709), EQ(EQC-91-235), EQ(EQC-91-894), EQ(EQC-92-062), EQ(EQC-93-162), EQ(EQC-94-008), ELS(ELSH-95-0269), VQ(VQH-06-010485)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Ceramic Co-fire

Assembly Information: See Note 1/

Assembly Flows: FC-25

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Package, Dual-in-line, Seam Weld, 7.48 Inch Seal Perimeter, 62 Leads, Gold/Solder Lead Finish; Ceramic Package, Leadless Chip Carrier, Solder Seal, 1.13 Inch Seal Perimeter, 22 Leads, Solder Lead Finish; Ceramic Package, Quad Flat Pack, Seam Weld, 6.20 Inch Seal Perimeter, 136 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Avago Technologies (CAGE Code: 50434)

No. 1 Yishun Avenue 7, Singapore, 768923

Company Contact: Ms. Shelley Sinclair, Phone: 408-435-4120, Fax: 408-435-4271, E-mail: shelley.sinclair@avagotech.com

DSCC Contact: Mr. Dan Miller, Phone: 614-692-2908, Fax: 614-692-6942, E-mail: vqh.dm@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Optocoupler

Qualification Letters: EQ(EQM-87-2594), EQ(EQM-88-1265), EQ(EQC-90-0754), EQ(EQC-93-271), EQ(EQC-93-591), ELS(ELSH-95-271), VQ(VQH-97-047), VQ(VQH-00-0109), VQ(VQH-01-0164), VQ(VQH-02-000432), VQ(VQH-02-001278), VQ(VQH-04-006618), VQ(VQH-04-006839)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Thick Film

Assembly Information: See Note 1/

Assembly Flows: ICPI-9001-3

Substrate Attach: Eutectic, Solder, Silver Glass

Element Attach: Eutectic, Silver Glass

Add-on Elements: Unpackaged Die

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Package, Dual-in-line, Solder Seal, 1.28 Inch Seal Perimeter, 16 Leads, Gold/Solder Lead Finish; Ceramic Package, Leadless Chip Carrier, Solder Seal, .92 Inch Seal Perimeter, 20 Leads, Solder Lead Finish; Ceramic Package, Peripheral Leads, Solder Seal, 1.32 Inch Seal Perimeter, 16 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

BI Technologies Corporation (CAGE Code: 73138)

4200 Bonita Place, Fullerton, CA 92835-1053, US

Company Contact: Ms. Blanca Perez, Phone: 619-368-9120, Fax: 714-447-2394, E-mail: blancaperez@bitechnologies.com

DSCC Contact: Mr. Christopher Hancock, Phone: 614-692-1309, Fax: 614-692-6942, E-mail: vqh.ch@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Voltage Regulator, Data Converters, Analog

Qualification Letters: EQ(EQC-89-071), EQ(EQC-91-718), EQ(EQC-92-382), EQ(EQC-92-383), VQH-97-0081, VQ(VQH-00-0095), VQ(VQH-10-020568)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 800-403-2

Substrate Fabrication: Thick Film on Alumina, 3 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: 800-403-03

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Tabs, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Peripheral Leads, Seam Weld, 5.86 Inch Seal Perimeter, 61 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Seam Weld, 6.87 Inch Seal Perimeter, 44 Leads, Gold Lead Finish; Ceramic Co-fire Package, Flatpack, Seam Weld, 1.04 Inch Seal Perimeter, 10 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

CMC Electronics Incorporated (CAGE Code: 90073)

600 Dr. Frederik Philips Boulevard, Ville Saint Laurent, Quebec, H4M 2S9, Canada

Company Contact: Mr. Jean-Marc Perreault, Phone: 514-748-3000 x4871, Fax: 514-748-3100, E-mail: Jean-Marc.Perreault@cmcelectronics.ca

DSCC Contact: Mr. Christopher Hancock, Phone: 614-692-1309, Fax: 614-692-6942, E-mail: vqh.ch@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Voltage Regulator

Qualification Letters: EQ(EQC-91-720), EQ(EQC-92-427), VQ(VQH-98-0133), VQ(VQH-04-005582)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 411-146425-000

Substrate Fabrication: Thick Film on Alumina, 7 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: 411-146426-000

Substrate Attach: Nonconductive Epoxy, Conductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Seam Weld, 3.61 Inch Seal Perimeter, 16 Leads, Gold Lead Finish; Metal Package, Bathtub, Seam Weld, 4.30 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Metal Package, Flatpack, Seam Weld, 1.56 Inch Seal Perimeter, 44 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Cobham Sensor Systems (CAGE Code: 65628)

9404 Chesapeake Drive, San Diego, CA 92123-1388, US

Company Contact: Mr. Chuck Bagwell, Phone: 858-505-3668, Fax: 858-560-0291, E-mail: chuck.bagwell@cobhamdes.com

DSCC Contact: Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

Quality Management (QM) Program: TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: Microwave Amplifier, Microwave Filter, Microwave Custom (IMAs)

Qualification Letters: ELS(ELSH-94-199), VQ(VQH-96-226), VQ(VQH-96-227), VQ(VQH-97-0180), VQ(VQH-97-0181), VQ(VQH-00-0104)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Thin Film; Purchased Duriod; Purchased Polyimide/PWB Copper

Assembly Information: See Note 1/

Assembly Flows: 001775

Substrate Attach: Conductive Epoxy, Eutectic, Solder

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors, Toroids, Coils, Thermcon, Inductors, Attenuators, IC Package

Wire Bonding: Gold, Copper, Ribbon

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Peripheral Leads, Seam Weld, 4.00 Inch Seal Perimeter, 16 Leads, Gold Lead Finish; Aluminum/Stainless Steel Package, DC/Microwave Leads, Laser Weld, 12.50 Inch Seal Perimeter, 6 Leads; Aluminum/Stainless Steel Package, DC/Microwave Leads (Dual-Sided, Multi-Cavity), Laser Weld, 24.00 Inch Seal Perimeter, 4 Leads

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Crane Electronics Corporation (CAGE Code: 50821)

5 South 6th Road Box 26-143, KEPZ, Kaohsiung, Taiwan, R.O.C 806

Company Contact: Mr. Stacy Irwin, Phone: 425-895-5038, Fax: 425-869-7402, E-mail: stacy.irwin@crane-eg.com

DSCC Contact: Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: DC-DC Converter, EMI Filters

Qualification Letters: VQ(VQH-97-0266), VQ(VQH-99-0070), VQ(VQH-99-0134), VQ(VQH-99-0175), VQ(VQH-99-0200), VQ(VQH-01-0017), VQ(VQH-01-0060), VQ(VQH-02-001187), VQ(VQH-03-004414), VQ(VQH-04-006128), VQ(VQH-04-006855), VQ(VQH-05-008873), VQ(VQH-06-010206), VQ(VQH-06-011675), VQ(VQH-07-012130), VQ(VQH-07-012468), VQ(VQH-10-019428), VQ(VQH-10-019429), VQ(VQH-10-020020), VQ(VQH-11-021213), VQ(VQH-11-021614), VQ(VQH-11-021809), VQ(VQH-11-021810), VQ(VQH-11-021879), VQ(VQH-11-021880)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: QA-039

Substrate Fabrication: Thick Film on Alumina, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 3 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: QA-039

Substrate Attach: Solder, Nonconductive RTV, Conductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Inductors, Toroids, Daughter Board

Wire Bonding: Gold, Aluminum, Copper

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Projection Weld, 5.14 Inch Seal Perimeter, 8 Leads, Gold Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 8.00 Inch Seal Perimeter, 20 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Crane Electronics, Inc. (CAGE Code: 50821)

10301 Willows Road, Redmond, WA 98052, US

Company Contact: Mr. Stacy Irwin, Phone: 425-895-5038, Fax: 425-869-7402, E-mail: stacy.irwin@crane-eg.com

DSCC Contact: Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Linear Amplifier, Signal Processor, Data Converters, DC/DC Converters, Analog, Digital, EMI Filters

Qualification Letters: EQ(EQM-87-2838), EQ(EQM-89-0439), EQ(EQC-92-174), EQ(EQC-92-300), EQ(EQC-93-031), EQ(EQC-93-056), EQ(EQC-93-196), EQ(EQC-93-221), EQ(EQC-93-280), EQ(EQC-93-550), EQC-93-624, EQ(EQM-94-043), EQ(EQM-94-0111), ELS(ELSH-94-0297), ELS(ELSH-94-0336), ELS(ELSH-94-0364), ELS(ELSH-95-0036), ELS(ELSH-95-0375), ELS(ELSH-96-0095), ELS(ELSH-96-0139), VQ(VQH-96-0214), VQ(VQH-98-0253), VQ(VQH-99-0013), VQ(VQH-00-0131), VQ(VQH-00-0188), VQ(VQH-03-003336), VQ(VQH-03-003760), VQ(VQH-04-006128), VQ(VQH-05-007236 AMENDED), VQ(VQH-05-008263), VQ(VQH-05-008516), VQ(VQH-05-008820), VQ(VQH-07-012129), VQ(VQH-07-012467), VQ(VQH-07-013397), VQ(VQH-13-026724)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: QA-039

Substrate Fabrication: Thick Film on Alumina, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 1 Conductor Level(s); Purchased Direct Bonded Copper

Assembly Information: See Note 1/

Assembly Flows: QA-039

Substrate Attach: Solder, Nonconductive Epoxy, Conductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic, RTV

Add-on Elements: Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Inductors, Toroids, Daughter Board

Wire Bonding: Gold, Aluminum, Copper

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Projection Weld, 4.26 Inch Seal Perimeter, 8 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 4.00 Inch Seal Perimeter, 32 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 8.75 Inch Seal Perimeter, 12 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 6.40 Inch Seal Perimeter, 5 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 6.00 Inch Seal Perimeter, 38 Leads, Gold/Solder Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Data Device Corporation (CAGE Code: 19645)

105 Wilbur Place, Bohemia, NY 11716-2482, US

Company Contact: Mr. John Young, Phone: 631-567-5600 x7246, Fax: 631-244-8252, E-mail: young@ddc-web.com

DSCC Contact: Mr. Joseph Buben II, Phone: 614-692-0592, Fax: 614-692-6942, E-mail: vqh.jbu@dla.mil

Quality Management (QM) Program: TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: 1553 Bus, Data Converters, Power

Qualification Letters: EQ(EQC-90-220), EQ(EQC-90-657), EQ(EQC-91-104), EQ(EQC-91-306), EQ(EQC-91-308), EQ(EQC-91-386), EQ(EQC-91-606), EQ(EQC-91-667), EQ(EQC-93-055), EQ(EQC-93-199), EQ(EQC-93-599), EQ(EQC-93-625), ELS(ELSH-94-0327), ELS(ELSH-94-0392), ELS(ELSH-94-0399), ELS(ELSH-95-0140), ELS(ELSH-95-0266), VQ(VQH-96-0203), VQ(VQH-98-0101), VQ(VQH-99-0033), VQ(VQH-99-0129), VQ(VQH-99-0222), VQ(VQH-02-0969), VQ(VQH-03-3982), VQ(VQH-04-5821), VQ(VQH-04-6876), VQ(VQH-06-010110), VQ(VQH-07-013396), VQ(VQH-10-019748)

Class Level Information: See Note 6/

Class K, Class H, Class D, Class G, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 41638, 41639, 45552

Substrate Fabrication: Thick Film on Alumina, 4 Conductor Level(s), Resistors; Thin Film on Alumina, 1 Conductor Level(s); Thick Film on Beryllia, 1 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: 41634, 41635, 45552

Substrate Attach: Nonconductive Epoxy, Solder, Conductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Tabs, Transformers, Chip Resistors, Tantalum Capacitors, Ceramic Capacitors

Wire Bonding: Gold, Aluminum, Copper/Tin Solder

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Peripheral Leads, Seam Weld, 8.80 Inch Seal Perimeter, 16 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 10.26 Inch Seal Perimeter, 94 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Platform, Projection Weld, 5.38 Inch Seal Perimeter, 32 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 7.58 Inch Seal Perimeter, 82 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Axial Leads, Seam Weld, 7.34 Inch Seal Perimeter, 78 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Peripheral Leads, Seam Weld, 7.34 Inch Seal Perimeter, 78 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, Axial Leads, Seam Weld, 5.80 Inch Seal Perimeter, 70 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, Peripheral Leads, Seam Weld, 5.80 Inch Seal Perimeter, 70 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, Peripheral Leads, Seam Weld, 4.00 Inch Seal Perimeter, 81 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, Axial Leads, Seam Weld, 4.00 Inch Seal Perimeter, 81 Leads, Gold Lead Finish, Getter Qualified; Ceramic Co-fire Package, J-Leads, Solder Seal, 2.12 Inch Seal Perimeter, 40 Leads, Gold Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

International Rectifier Aerospace & Defense (CA) (CAGE Code: 52467)

2520 Junction Avenue, San Jose, CA 95134-1902, US

Company Contact: Mr. Granville 'Bo' Rains, Phone: 408-434-5086, Fax: 408-434-5220, E-mail: grains1@irf.com

DSCC Contact: Ms. Jonnie Schneider, Phone: 614-692-0585, Fax: 614-692-6942, E-mail: vqh.jms@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: DC/DC Converters

Advanced Semiconductor Engrg Inc, Nantou Branch

Qualification Letters: VQ(VQH-02-1624), VQ(VQH-05-009379)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: N/A

Assembly Information: See Note 1/

Assembly Flows: 8002-0044

Substrate Attach: Conductive Epoxy, Nonconductive Epoxy, Solder

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder

Add-on Elements: Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Transformers

Wire Bonding: Gold, Aluminum, Copper

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Seam Weld, 6.58 Inch Seal Perimeter, 10 Leads, Gold/Solder Lead Finish

Santa Clara Facility

Qualification Letters: EQ(EQC-89-065), EQ(EQC-90-652), EQ(EQC-92-103), EQ(EQC-93-204), EQ(EQC-93-403), EQ(EQC-93-553), EQ(EQC-93-658), ELS(ELSH-94-0173), ELS(ELSH-94-0211), ELS(ELSH-94-0212), ELS(ELSH-94-0272), ELS(ELSH-94-0482), ELS(ELSH-94-0483), VQ(VQH-98-0100), VQ(VQH-98-0231), VQ(VQH-03-003517), VQ(VQH-05-9326), VQ(VQH-06-011051), VQ(VQH-07-013935), VQ(VQH-08-015552), VQ(VQH-12-023788), VQ(VQH-13-026800)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 8002-0044

Substrate Fabrication: Thick Film on Alumina, 5 Conductor Level(s), Resistors; Thick Film on Beryllia, 4 Conductor Level(s), Resistors; Purchased Direct Bonded Copper

Assembly Information: See Note 1/

Assembly Flows: 8002-0044

Substrate Attach: Conductive Epoxy, Nonconductive Epoxy, Solder

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder, RTV, Elastomer

Add-on Elements: Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Tabs, Chip Resistors, Transformers, Inductors, Wires, Terminals

Wire Bonding: Gold, Aluminum, Copper

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Package, Dual-in-line, Seam Weld, 3.69 Inch Seal Perimeter, 24 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 6.58 Inch Seal Perimeter, 10 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 10.10 Inch Seal Perimeter, 58 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 8.00 Inch Seal Perimeter, 12 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 11.00 Inch Seal Perimeter, 13 Leads, Gold/Solder Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

International Rectifier Aerospace & Defense (MA) (CAGE Code: 69210)

205 Crawford Street, Leominster, MA 01453-2353, US

Company Contact: Ms. Cora Gustason, Phone: 978-466-5532, Fax: 978-537-4246, E-mail: cgustas1@irf.com

DSCC Contact: Ms. Jacqueline Cunningham, Phone: 614-692-0584, Fax: 614-692-6942, E-mail: vqh.jc@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Voltage Regulator, Power

Qualification Letters: EQ(EQC-91-408), EQ(EQC-91-807), EQ(EQC-91-838), EQ(EQM-94-0029), ELS(ELSH-94-0388), VQ(VQH-98-0014), VQ(VQH-01-0034), VQ(VQH-03-003838), VQ(VQH-08-016688), VQ(VQH-10-019960), VQ(VQH-10-020180), VQ(VQH-11-022643), VQ(VQH-12-024352), VQ(VQH-13-026659), VQ(VQH-13-026696)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: D050015G

Substrate Fabrication: Thick Film on Alumina, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 3 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: D050015G

Substrate Attach: Solder, Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder

Add-on Elements: Unpackaged Die, Chip Capacitors, Tabs, Chip Resistors, Encapsulated Hybrid

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Peripheral Leads, Seam Weld, 2.47 Inch Seal Perimeter, 8 Leads, Solder Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 8.80 Inch Seal Perimeter, 43 Leads, Gold Lead Finish; Metal Package, Axial Leads, Seam Weld, 4.08 Inch Seal Perimeter, 24 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Peripheral Leads, Seam Weld, 2.14 Inch Seal Perimeter, 19 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

L-3 Communications Cincinnati Electronics (CAGE Code: 80045)

7500 Innovation Way, Mason, OH 45040-9699, US

Company Contact: Ms. Jennifer Douglas, Phone: 513-573-6156, Fax: 513-573-6290, E-mail: Jennifer.Douglas@L-3Com.com

DSCC Contact: Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: Custom, Analog, Amplifier, Linear

Qualification Letters: VQ(VQH-98-0195), VQ(VQH-00-0167)

Class Level Information: See Note 6/

Class D

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 637140

Substrate Fabrication: Thick Film on Alumina, 7 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: 637143

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Radial Leads, Laser Weld, 8.00 Inch Seal Perimeter, 69 Leads, Gold Lead Finish

Qualification Letters: EQ(EQC-93-113), EQC-93-197, ELS(ELSH-94-417), VQ(VQH-01-0034), VQ(VQH-10-020213)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 637140

Substrate Fabrication: Thick Film on Alumina, 6 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: 637143

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Seam Weld, 3.48 Inch Seal Perimeter, 18 Leads, Gold Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 3.58 Inch Seal Perimeter, 20 Leads, Gold Lead Finish; Metal Package, Axial Leads, Seam Weld, 5.20 Inch Seal Perimeter, 30 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Lockheed Martin Missiles and Fire Control (CAGE Code: 04939)

5600 Sand Lake Road MP189, Orlando, FL 32819-8907, US

Company Contact: Ms. Kristina Lydiard, Phone: 407-356-5060, Fax: 407-356-6808, E-mail: kristina.lydiard@lmco.com

DSCC Contact: Ms. Jonnie Schneider, Phone: 614-692-0585, Fax: 614-692-6942, E-mail: vqh.jms@dla.mil

Quality Management (QM) Program: TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: Digital, Analog

Qualification Letters: EQ(EQC-91-402), EQ(EQC-91-764), EQ(EQC-92-112), EQ(EQC-92-312), EQ(EQC-92-412), VQ(VQH-99-0164), VQ(VQH-10-020356)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Thick Film

Assembly Information: See Note 1/

Assembly Flows: 72301772

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Chip Resistors, Inductors

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Package, Leadless Chip Carrier, Solder Seal, 3.80 Inch Seal Perimeter, 68 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Solder Seal, 2.88 Inch Seal Perimeter, 18 Leads, Gold/Solder Lead Finish; Metal Package, Platform, Projection Weld, 5.76 Inch Seal Perimeter, 44 Leads, Gold Lead Finish; Metal Package, Axial Leads, Seam Weld, 11.80 Inch Seal Perimeter, 140 Leads, Gold Lead Finish

Qualification Letters: VQ(VQH-12-024704)

Class Level Information: See Note 6/

Class D

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Thick Film

Assembly Information: See Note 1/

Assembly Flows: 861 Process Flow

Substrate Attach: Solder

Element Attach: Conductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitor

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Projection Weld, 1.88 Inch Seal Perimeter, 16 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

M.S. Kennedy Corporation (CAGE Code: 51651)

4707 Dey Road, Liverpool, NY 13088-3510, US

Company Contact: Mr. Daniel Miller, Phone: 315-701-6751, Fax: 315-701-6752, E-mail: d.miller@mskennedy.com

DSCC Contact: Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: High Power Amplifiers, Amplifiers, PWB H-Bridge, Custom Hybrids/MCMs, Voltage Regulator, Switching Regulator, RAD HARD Hybrids, Motor Controllers, Linear Regulators, DC/DC Converters, Filters, Video Amplifiers

Qualification Letters: EQ(EQC-90-451), EQ(EQC-90-507), EQ(EQC-92-417), EQ(EQC-93-141), EQ(EQC-93-242), EQ(EQC-93-346), EQ(EQC-93-488), EQ(EQC-93-554), EQ(EQC-93-682), EQ(EQC-93-687), EQ(EQM-94-084), EQ(EQM-94-093), ELS(ELSH-94-0400), ELS(ELSH-94-0401), ELS(ELSH-94-0402), ELS(ELSH-94-0470), ELS(ELSH-95-0020), ELS(ELSH-95-0216), ELS(ELSH-95-0304), ELS(ELSH-96-0073), ELS(ELSH-96-0086), VQ(VQH-96-0206), VQ(VQH-97-0046), VQ(VQH-97-0073), VQ(VQH-97-0089), VQ(VQH-97-0223), VQ(VQH-97-0228), VQ(VQH-97-0238), VQ(VQH-97-0243), VQ(VQH-98-0246), VQ(VQH-99-0145), VQ(VQH-00-0023), VQ(VQH-00-0242), VQ(VQH-01-0065), VQ(VQH-01-0075), VQ(VQH-02-000095), VQ(VQH-03-002841), VQ(VQH-03-003922), VQ(VQH-03-004192), VQ(VQH-03-004194), VQ(VQH-04-005084), VQ(VQH-04-005148), VQ(VQH-04-005646), VQ(VQH-04-006786), VQ(VQH-04-006941), VQ(VQH-04-007061), VQ(VQH-04-007098), VQ(VQH-05-008546), VQ(VQH-05-008816), VQ(VQH-05-008994), VQ(VQH-05-008995), VQ(VQH-06-009631), VQ(VQH-06-009683), VQ(VQH-06-009742), VQ(VQH-06-010016), VQ(VQH-06-010082), VQ(VQH-06-010086), VQ(VQH-06-010359), VQ(VQH-06-010509), VQ(VQH-06-010846), VQ(VQH-06-011516), VQ(VQH-07-012278), VQ(VQH-07-012548), VQ(VQH-07-013658), VQ(VQH-08-014579), VQ(VQH-08-014909), VQ(VQH-09-016693), VQ(VQH-09-018310), VQ(VQH-09-018313), VQ(VQH-09-018466), VQ(VQH-09-018978), VQ(VQH-10-021073), VQ(VQH-11-022826), VQ(VQH-11-022827), VQ(VQH-11-022828), VQ(VQH-11-023107), VQ(VQH-11-023174), VQ(VQH-11-023234), VQ(VQH-12-024146), VQ(VQH-13-025668)

Class Level Information: See Note 6/

Class K, Class H, Class G, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 2422-1563

Substrate Fabrication: Thick Film on Alumina, 2 Conductor Level(s), Resistors; Thick Film on Alumina, 6 Conductor Level(s); Purchased Alumina/Copper; Thick Film on Beryllia, 3 Conductor Level(s), Resistors; Thick Film on Beryllia, 1 Conductor Level(s); Purchased Alumina

Assembly Information: See Note 1/

Assembly Flows: 2422-1518

Substrate Attach: Conductive Epoxy, Nonconductive Epoxy, Solder

Element Attach: Solder, Conductive Epoxy, Nonconductive Epoxy, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Tabs, Chip Resistors, Inductors, Bonding Block, Daughter Board, Crystal, Ceramic Posts

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, TO Can, Projection Weld, 3.14 Inch Seal Perimeter, 12 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Platform, Projection Weld, 2.60 Inch Seal Perimeter, 14 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 5.00 Inch Seal Perimeter, 44 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 6.95 Inch Seal Perimeter, 82 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 6.00 Inch Seal Perimeter, 12 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Brazed Leads, Solder Seal, 2.06 Inch Seal Perimeter, 28 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Surface Mount, Seam Weld, 2.15 Inch Seal Perimeter, 3 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Peripheral Leads, Seam Weld, 4.79 Inch Seal Perimeter, 10 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, Flatpack, Seam Weld, 2.38 Inch Seal Perimeter, 10 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Flatpack, Seam Weld, 5.98 Inch Seal Perimeter, 196 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Flatpack, Solder Seal, 1.33 Inch Seal Perimeter, 14 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Bathtub, Seam Weld, 2.45 Inch Seal Perimeter, 5 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, LCC, Solder Seal, 1.40 Inch Seal Perimeter, 20 Leads, Gold Lead Finish, Getter Qualified; Ceramic Package, LCC, Seam Weld, 2.16 Inch Seal Perimeter, 3 Leads, Gold Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Micropac Industries, Incorporated (CAGE Code: 31757)

905 East Walnut Street, Garland, TX 75040-6696, US

Company Contact: Mr. Cecil Miller, Phone: 972-272-3571, Fax: 972-494-2281, E-mail: cmiller@micropac.com

DSCC Contact: Mr. Dan Miller, Phone: 614-692-2908, Fax: 614-692-6942, E-mail: vqh.dm@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Custom, Power, Optocouplers

Inmobiliaria San Jose De Co. Plant

Qualification Letters: VQ(VQH-04-005466), VQ(VQH-06-010381), VQ(VQH-06-011928)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: N/A

Assembly Information: See Note 1/

Assembly Flows: 90138

Substrate Attach: N/A

Element Attach: Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Resistors, Spacer

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: N/A

Micropac Custom Line, Garland TX

Qualification Letters: EQ(EQC-91-178), EQ(EQC-91-647), EQ(EQC-92-183), EQ(EQC-92-258), VQ(VQH-04-006232), VQ(VQH-05-008704), VQ(VQH-05-009200), VQ(VQH-05-009466), VQ(VQH-06-011928), VQ(VQH-07-012661), VQ(VQH-07-013773)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 90138

Substrate Fabrication: Thick Film on Alumina, 5 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: 90138

Substrate Attach: Nonconductive Epoxy, Solder

Element Attach: Eutectic, Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Seam Weld, 5.00 Inch Seal Perimeter, 28 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 5.00 Inch Seal Perimeter, 46 Leads, Gold/Solder Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Micropac Industries, Incorporated (CAGE Code: 31757)

905 East Walnut Street, Garland, TX 75040-6696, US

Company Contact: Mr. Cecil Miller, Phone: 972-272-3571, Fax: 972-494-2281, E-mail: cmiller@micropac.com

DSCC Contact: Mr. Dan Miller, Phone: 614-692-2908, Fax: 614-692-6942, E-mail: vqh.dm@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Custom, Power, Optocouplers

Micropac Opto Line, Garland TX

Qualification Letters: EQ(EQC-90-624), EQ(EQC-91-188), EQ(EQC-91-466), EQ(EQC-92-120), ELS(ELSH-95-0057), ELS(ELSH-95-0444), VQ(VQH-04-006232), VQ(VQH-05-008721), VQ(VQH-12-025123)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 90138

Substrate Fabrication: Thick Film on Alumina, 2 Conductor Level(s), Resistors; Thick Film on Alumina, 1 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: 90138

Substrate Attach: Conductive Epoxy, Nonconductive Epoxy

Element Attach: Eutectic, Conductive Epoxy

Add-on Elements: Unpackaged Die, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Package, Dual-in-line, Solder Seal, 1.89 Inch Seal Perimeter, 16 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Leadless Chip Carrier, Solder Seal, 1.60 Inch Seal Perimeter, 24 Leads, Solder Lead Finish, Getter Qualified; Metal Package, TO Can (dual base), Projection Weld, .54 Inch Seal Perimeter, 7 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Dual-in-line, Seam Weld, 1.33 Inch Seal Perimeter, 8 Leads, Gold/Solder Lead Finish, Getter Qualified

Micropac Power Line, Garland TX

Qualification Letters: EQ(EQC-90-625), EQ(EQC-91-328), EQ(EQC-91-338), EQ(EQC-92-183), EQ(EQC-92-258), ELS(ELSH-94-0496), VQ(VQH-04-006232), VQ(VQH-05-007911), VQ(VQH-05-009200), VQ(VQH-06-011765), VQ(VQH-07-013121), VQ(VQH-08-015994), VQ(VQH-12-025067)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 90138

Substrate Fabrication: Thick Film on Alumina, 1 Conductor Level(s), Resistors; Thick Film on Beryllia, 2 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: 90138

Substrate Attach: Nonconductive Epoxy, Solder

Element Attach: Conductive Epoxy, Solder, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, TO Can, Projection Weld, 2.27 Inch Seal Perimeter, 8 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Dual-in-line, Seam Weld, 1.36 Inch Seal Perimeter, 8 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Micro-Precision Technologies, Inc. (CAGE Code: 0F962)

10 Manor Parkway, Salem, NH 03079-2841, US

Company Contact: Dr. Etang Chen, Phone: 603-893-7600, Fax: 603-893-9110, E-mail: ec@micropt.com

DSCC Contact: Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: Yes

Technologies: Linear, Digital, Analog

Qualification Letters: VQ(VQH-00-0004), VQ(VQH-10-019928)

Class Level Information: See Note 6/

Class H, Class G, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: CP9146-Screening Rev. -

Substrate Fabrication: Thick Film on Alumina, 3 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: CP9146Q-Assembly Traveler Rev. -

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder

Add-on Elements: Unpackaged Die, Chip Resistors, Chip Capacitors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Peripheral Leads, Seam Weld, 6.32 Inch Seal Perimeter, 65 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Microsemi Corporation Lawrence (CAGE Code: 43611)

3 South Side Road, Danvers, MA 01923-1408, US

Company Contact: Mr. Charlie Yiakas, Phone: 978-774-8722, Fax: 978-774-0939, E-mail: cyiakas@microsemi.com

DSCC Contact: Mr. Christopher Hancock, Phone: 614-692-1309, Fax: 614-692-6942, E-mail: vqh.ch@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 2

Approved ISO 9000 System: No

Technologies: Solid State Switch

Qualification Letters: VQ(VQH-12-024364), VQ(VQH-12-025103)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 7-458K

Substrate Fabrication: Thick Film on Alumina, 1 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: MHS2505DRH

Substrate Attach: Solder, Nonconductive Epoxy

Element Attach: Conductive Epoxy, Eutectic, Solder, Nonconductive Epoxy

Add-on Elements: Daughter Board, Chip Capacitors, Tabs, Unpackaged Die, Chip Resistors

Wire Bonding: Aluminum, Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Flatpack, Seam Weld, 3.85 Inch Seal Perimeter, 8 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Microsemi Power & Microelectronics Group (CAGE Code: 54230)

3601 East University Drive, Phoenix, AZ 85034-7217, US

Company Contact: Ms. Usha Shah, Phone: 602-437-1520 x13225, Fax: 602-437-9120, E-mail: ushah@wedc.com

DSCC Contact: Ms. Jacqueline Cunningham, Phone: 614-692-0584, Fax: 614-692-6942, E-mail: vqh.jc@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Digital Memory

Qualification Letters: EQ(EQC-90-019), EQ(EQC-92-070), EQ(EQC-92-138), EQC-93-457, EQ(EQC-93-508), ELS(ELSH-94-0256), ELS(ELSH-95-0107), ELS(ELSH-95-0365), ELS(ELSH-96-0014), ELS(ELSH-96-0184), ELS(ELSH-96-0186), VQ(VQH-96-0210), VQ(VQH-96-0211), VQ(VQH-97-0016), VQ(VQH-97-0170), VQ(VQH-98-0172), VQ(VQH-99-0258), VQ(VQH-00-0079)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Thick Film; Purchased Ceramic Co-fire

Assembly Information: See Note 1/

Assembly Flows: 035A00001

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Co-fire Package, Brazed Leads, Seam Weld, 5.36 Inch Seal Perimeter, 68 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Co-fire Package, Axial Leads, Seam Weld, 4.58 Inch Seal Perimeter, 66 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Pin Grid Array, Seam Weld, 4.10 Inch Seal Perimeter, 66 Leads, Gold Lead Finish, Getter Qualified

Amertron Inc. (Philippines)

Qualification Letters: VQ(VQH-12-024754)

Class Level Information: See Note 6/

Class H

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Ceramic Co-fire

Assembly Information: See Note 1/

Assembly Flows: 035A00001

Substrate Attach: N/A

Element Attach: Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors

Wire Bonding: N/A

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Co-fire Package, Brazed Leads, Seam Weld, 3.32 Inch Seal Perimeter, 68 Leads, Gold/Solder Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Micross Components, Austin (CAGE Code: 0EU86)

8701 Cross Park Drive, Austin, TX 78754-4566, US

Company Contact: Mr. Allen Wares, Phone: 512-339-1188 x7138, Fax: 512-339-6641, E-mail: Allen.Wares@micross.com

DSCC Contact: Mr. Joseph Buben II, Phone: 614-692-0592, Fax: 614-692-6942, E-mail: vqh.jbu@dla.mil

Quality Management (QM) Program: TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: Memory

Micross Components, Austin

Qualification Letters: VQ(VQH-99-0144), VQ(VQH-05-009274), VQ(VQH-05-009315), VQ(VQH-05-009388), VQ(VQH-05-009621), VQ(VQH-06-009807), VQ(VQH-06-010137), VQ(VQH-06-010562), VQ(VQH-06-010804), VQ(VQH-07-012340), (VQ(VQH-09-017567)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: N/A

Assembly Information: See Note 1/

Assembly Flows: 2/ASI-H/512K32F1/A, 1595, 1648, AS85512K32P-SAD, S51232MA, R12832MA

Substrate Attach: N/A

Element Attach: Ag Cyanate Ester, Eutectic, Noncond. Cyanate Ester, Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Co-fire Package, Quad Flat Pack, Solder Seal, 1.76 Inch Seal Perimeter, 68 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Solder Seal, 1.44 Inch Seal Perimeter, 14 Leads, Solder Lead Finish; Ceramic Co-fire Package, Pin Grid Array, Seam Weld, 4.06 Inch Seal Perimeter, 66 Leads, Gold/Solder Lead Finish; Ceramic Co-fire Package, Quad Flat Pack, Seam Weld, 3.34 Inch Seal Perimeter, 68 Leads, Gold/Solder Lead Finish; Ceramic Co-fire Package, Quad Flat Pack, Seam Weld, 5.60 Inch Seal Perimeter, 68 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Murata Power Solutions Inc. (DATEL) (CAGE Code: 50721)

11 Cabot Boulevard, Mansfield, MA 02048-1194, US

Company Contact: Mr. Tim Brown, Phone: 508-339-3000, Fax: 508-339-6356, E-mail: Tim.Brown@murata-ps.com

DSCC Contact: Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Digital

Qualification Letters: EQ(EQC-90-626), EQ(EQC-90-677), EQ(EQC-91-029), EQ(EQC-92-446), ELS(ELSH-95-0356), VQ(VQH-97-0084), VQ(VQH-98-0261), VQ(VQH-07-012296), VQ(VQH-10-019587), VQ(VQH-11-022867)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: D-4552

Substrate Fabrication: Thick Film on Alumina, 7 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: D-4552

Substrate Attach: Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Tantalum Capacitors, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Package, Dual-in-line, Seam Weld, 7.24 Inch Seal Perimeter, 62 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Natel Carson City Operations (CAGE Code: 0ANM4)

400 Hot Springs Road, Carson City, NV 89706-1609, US

Company Contact: Mrs. Kathy Cano, Phone: 775-883-0820, Fax: 775-883-0827, E-mail: kcano@natelengr.com

DSCC Contact: Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Active Delay Line, Linear, Custom Hybrid

Qualification Letters: EQ(EQC-91-859), EQ(EQM-94-0023), EQ(EQM-94-0102), VQ(VQH-04-006262), VQ(VQH-05-007828), VQ(VQH-06-010743), VQ(VQH-07-012497), VQ(VQH-08-015017), VQ(VQH-08-015553), VQ(VQH-09-016945), VQ(VQH-10-020918)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: RN1005-002, 8111663

Substrate Fabrication: Thick Film on Alumina, 2 Conductor Level(s), Resistors; Thick Film on Beryllia, 1 Conductor Level(s); Thick Film on Ceramic, 7 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: RN1005-004

Substrate Attach: Nonconductive Epoxy, Conductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Inductors, Chip Resistors, Tabs, Tantalum Capacitors, Quartz Crystal, Ceramic Stand Off

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Platform, Projection Weld, 2.94 Inch Seal Perimeter, 16 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 6.32 Inch Seal Perimeter, 48 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 5.00 Inch Seal Perimeter, 56 Leads, Nickel Lead Finish, Getter Qualified; Ceramic Co-fire Package, Brazed Leads, Seam Weld, 2.47 Inch Seal Perimeter, 11 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Natel Engineering Company, Inc. (CAGE Code: 09059)

9340 Owensmouth Avenue, Chatsworth, CA 91311-6915, US

Company Contact: Mr. Jay Klug, Phone: 818-734-6568, Fax: 818-734-6540, E-mail: jklug@natelengr.com

DSCC Contact: Ms. Jonnie Schneider, Phone: 614-692-0585, Fax: 614-692-6942, E-mail: vqh.jms@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 2

Approved ISO 9000 System: No

Technologies: Hybrid Microcircuits, Custom Hybrids, Multichip Modules

Qualification Letters: EQ(EQC-91-714), EQ(EQC-92-039), EQ(EQC-92-048), EQ(EQC-92-202), EQ(EQC-93-261), ELS(ELSH-95-0154), ELS(ELSH-95-0314), VQ(VQH-01-156), VQ(VQH-03-004107)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Direct Bonded Copper; Purchased Thick Film on Beryllia/Alumina, 1 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: NHPS-01.001, NPS-01.016

Substrate Attach: Nonconductive Epoxy, Conductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Eutectic

Add-on Elements: Ceramic Posts, Chip Capacitors, Chip Resistors, Daughter Board, Unpackaged Die

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Peripheral Leads, Seam Weld, 5.34 Inch Seal Perimeter, 36 Leads, Gold Lead Finish; Metal Package, Axial Leads, Seam Weld, 6.56 Inch Seal Perimeter, 40 Leads, Gold Lead Finish; Metal Package, Single-in-line, Seam Weld, 4.34 Inch Seal Perimeter, 14 Leads, Nickel Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Pantronix Corporation (CAGE Code: 2V289)

2710 Lakeview Court, Fremont, CA 94538, US

Company Contact: Mr. Solomon Ching, Phone: 510-656-5898, Fax: 510-656-7779, E-mail: sching@pantronix.com

DSCC Contact: Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: Custom, Digital, Analog

Qualification Letters: VQ(VQH-06-010701)

Class Level Information: See Note 6/

Class D

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased LTCC on Ceramic, 10 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: 710-023

Substrate Attach: N/A

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Eutectic, Silver Glass

Add-on Elements: Unpackaged Die, Chip Resistors, Chip Capacitors, Ceramic Posts

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Package, Quad Flat Pack, Seam Weld, 5.38 Inch Seal Perimeter, 270 Leads, Gold Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Precision Devices Incorporated (CAGE Code: 0S4G1)

8840 N. Greenview Drive, Middleton, WI 53562, US

Company Contact: Mr. Chris Harden, Phone: 608-203-0230, Fax: 608-831-3343, E-mail: Chris_H@pdixtal.com

DSCC Contact: Ms. Jonnie Schneider, Phone: 614-692-0585, Fax: 614-692-6942, E-mail: vqh.jms@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 2

Approved ISO 9000 System: No

Technologies: Crystal oscillator, Hybrid assemblies

Qualification Letters: VQ(VQH-05-007968), VQ(VQH-12-024419)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased FR4 printed circuit board, 2 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: CP 7.5.1.38-A, cp 7.5.1.40-A

Substrate Attach: Solder

Element Attach: Solder

Add-on Elements: surface mount (smd) caps, smd resistors, smd plastic active device, smd ceramic active device, metal canned crystals, smd ceramic crystals

Wire Bonding: N/A

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Dual-in-line, Projection Weld, 2.85 Inch Seal Perimeter, 14 Leads, Solder Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 7.18 Inch Seal Perimeter, 24 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

RF2M Microelectronics Ltd. (CAGE Code: U4388)

South Denes, Great Yarmouth, Norfolk NR30 3PX, England

Company Contact: Mr. Mark Whelband, Phone: 1493-743121, Fax: 1493-858536, E-mail: Mark.Whelband@apitech.com

DSCC Contact: Mr. Joseph Buben II, Phone: 614-692-0592, Fax: 614-692-6942, E-mail: vqh.jbu@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: 1553 Transceiver, High Voltage Drivers, Power

Qualification Letters: EQ(EQC-91-835), EQ(EQC-92-084), EQ(EQC-93-139), ELS(ELSH-96-0054), ELS(ELSH-96-0161), VQ(VQH-98-0227), VQ(VQH-99-0192), VQ(VQH-99-0196), VQ(VQH-04-006510), VQ(VQH-04-007022), VQ(VQH-04-007023), VQ(VQH-05-008727), VQ(VQH-05-008978), VQ(VQH-06-010730), VQ(VQH-06-011795), VQ(VQH-09-017847), VQ(VQH-10-020173), VQ(VQH-10-020296), VQ(VQH-13-025883)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: FCES 6301:15

Substrate Fabrication: Purchased Ceramic Co-fire; Thick Film on Alumina, 4 Conductor Level(s), Resistors; Purchased Direct Bonded Copper on Beryllia

Assembly Information: See Note 1/

Assembly Flows: FCES 6301:15

Substrate Attach: Conductive Epoxy, Nonconductive Epoxy, Solder

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors, Transformers, Ceramic Tabs

Wire Bonding: Gold, Aluminum, Aluminum Ribbon

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Seam Weld, 5.30 Inch Seal Perimeter, 36 Leads, Gold/Solder Lead Finish; Metal Package, Peripheral Leads, Seam Weld, 5.30 Inch Seal Perimeter, 36 Leads, Gold/Solder Lead Finish; Metal Package, Axial Leads, Projection Weld, 4.37 Inch Seal Perimeter, 24 Leads, Gold/Solder Lead Finish; Ceramic Package, Pin Grid Array, Seam Weld, 5.00 Inch Seal Perimeter, 101 Leads, Gold Lead Finish; Metal Package, TO can, Projection Weld, 1.13 Inch Seal Perimeter, 10 Leads, Gold/Solder Lead Finish; Ceramic Co-fire Package, Dual-in-line, Seam Weld, 2.53 Inch Seal Perimeter, 24 Leads, Gold Lead Finish; Ceramic Package, Dual-in-line, Seam Weld, 5.38 Inch Seal Perimeter, 32 Leads, Gold Lead Finish; Ceramic Package, Quad Flat Pack, Seam Weld, 3.48 Inch Seal Perimeter, 68 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Robins AFB (CAGE Code: 0RCH2)

402 EMXSS/MXDEAD, 420 Richard Ray Blvd Ste 100, Robins AFB, GA 31098-1640, US

Company Contact: Ms. Kimberly Dockery, Phone: 478-926-9472, Fax: 478-926-9234, E-mail: Kimberly.Dockery@ROBINS.AF.MIL

DSCC Contact: Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: I/Q Phase Detector, Digibus

Qualification Letters: VQ(VQH-00-0107), VQ(VQH-07-012450), VQ(VQH-13-025669)

Class Level Information: See Note 6/

Class H, Class G, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Thick Film on Alumina, 4 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: PCD0200

Substrate Attach: Conductive Epoxy, Nonconductive Epoxy

Element Attach: Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Flatpack, Seam Weld, 5.92 Inch Seal Perimeter, 68 Leads, Gold Lead Finish; Ceramic Package, Flatpack, Seam Weld, 4.02 Inch Seal Perimeter, 30 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Sensitron Semiconductor (CAGE Code: 13409)

221 West Industry Court, Deer Park, NY 11729-4681, US

Company Contact: Ms. Marilyn Schroh, Phone: 631-586-7600, Fax: 631-586-7652, E-mail: marilyn.schroh@rsm.com

DSCC Contact: Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Power, Transistors

Qualification Letters: N/A

Class Level Information: See Note 6/

Class D

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Beryllia; Purchased Alumina

Assembly Information: See Note 1/

Assembly Flows: 7710-0582

Substrate Attach: Solder

Element Attach: Solder

Add-on Elements: Packaged FET, Chip Resistors, Chip Capacitors

Wire Bonding: Copper

Package Information: See Notes 1/ 2/ 3/

Package Information: Epoxy Package, Axial Leads, Epoxy Seal, 4.64 Inch Seal Perimeter, 16 Leads, Copper Lead Finish

Qualification Letters: VQ(VQH-00-0119), VQ(VQH-00-0168), VQ(VQH-00-0169), VQ(VQH-03-002777)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Aluminum Nitride

Assembly Information: See Note 1/

Assembly Flows: 7710-0582

Substrate Attach: Solder

Element Attach: Conductive Epoxy, Solder, Eutectic

Add-on Elements: Unpackaged Die, Chip Resistors

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Seam Weld, 4.00 Inch Seal Perimeter, 12 Leads, Gold Lead Finish; Metal Package, Solder Seal, 1.96 Inch Seal Perimeter; Metal Package, TO Can, Projection Weld, 1.13 Inch Seal Perimeter, 8 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Solitron Devices, Incorporated (CAGE Code: 21845)

3301 Electronics Way, West Palm Beach, FL 33407-4697, US

Company Contact: Mr. Arthur France, Phone: 561-848-4311, Fax: 561-863-5946, E-mail: afrance@solitrondevices.com

DSCC Contact: Mr. Dan Miller, Phone: 614-692-2908, Fax: 614-692-6942, E-mail: vqh.dm@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Linear, Power, Voltage Regulator

Qualification Letters: ELS(ELSH-94-0316), ELS(ELSH-94-0433), ELS(ELSH-95-0079), ELS(ELSH-95-0210), VQ(VQH-99-0180), VQ(VQH-99-0195), VQ(VQH-00-0125), VQ(VQH-03-003255), VQ(VQH-03-004107), VQ(VQH-05-007716)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: H1043

Substrate Fabrication: Thick Film on Alumina, 1 Conductor Level(s), Resistors; Thick Film on Beryllia, 2 Conductor Level(s), Resistors; Thick Film on Beryllia, 2 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: H1040

Substrate Attach: Eutectic, Solder

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Eutectic, Solder

Add-on Elements: Unpackaged Die, Chip Capacitors, Tabs

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, TO Can, Projection Weld, 2.86 Inch Seal Perimeter, 3 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 4.64 Inch Seal Perimeter, 6 Leads, Gold/Solder Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Teledyne Microelectronic Technologies (CAGE Code: 16170)

12964 Panama Street, Los Angeles, CA 90066-6534, US

Company Contact: Mr. Evon Bennett, Phone: 310-574-2004, Fax: 310-574-2093, E-mail: ebennett@teledyne.com

DSCC Contact: Mr. Richard Barker, Phone: 614-692-0596, Fax: 614-692-6942, E-mail: vqh.rb@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Approved ISO 9000 System: No

Technologies: Data Converters, Linear, Microwave, Custom, Power, RF Microwave

Qualification Letters: VQ(VQH-06-10253)

Class Level Information: See Note 6/

Class D

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 8575200-1, 2303506

Substrate Fabrication: Thick Film on Alumina, 7 Conductor Level(s), Resistors; Thin Film on Alumina, 1 Conductor Level(s), Resistors; Purchased Thick Film on Alumina

Assembly Information: See Note 1/

Assembly Flows: 7700530

Substrate Attach: Nonconductive Epoxy, Solder

Element Attach: Nonconductive Epoxy, Conductive Epoxy, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors, stiffener plate, Tabs, Inductors, Transformers, Chip Resistors

Wire Bonding: Gold, Aluminum, Ribbon

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Peripheral Leads, Seam Weld, 10.90 Inch Seal Perimeter, 92 Leads, Gold Lead Finish, Getter Qualified

Qualification Letters: EQ(EQM-87-1898), EQ(EQC-91-897), EQ(EQM-94-0085), EQ(EQM-94-0098), EQ(EQM-94-138), ELS(ELSH-94-313), VQ(VQH-00-0081), VQ(VQH-04-006032), VQ(VQH-05-7258), VQ(VQH-10-019408), VQ(VQH-10-019950), VQ(VQH-11-021450), VQ(VQH-11-021451), VQ(VQH-11-021452)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 8575200-1, 2303506

Substrate Fabrication: Thin Film on Alumina, 1 Conductor Level(s), Resistors; Thick Film on Alumina, 7 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: 7700530

Substrate Attach: Nonconductive Epoxy, Solder

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors

Wire Bonding: Gold, Aluminum, Ribbon

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Peripheral Leads, Seam Weld, 8.75 Inch Seal Perimeter, 94 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Axial Leads, Seam Weld, 5.00 Inch Seal Perimeter, 24 Leads, Gold Lead Finish, Getter Qualified; Metal Package, Side Brazed Leads, Seam Weld, 6.60 Inch Seal Perimeter, 136 Leads, Gold Lead Finish, Getter Qualified

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

Teledyne Microwave Solutions (CAGE Code: 0D4L1)

927 Thompson Place, Sunnyvale, CA 94085-4518, US

Company Contact: Ms. Dory Maciel, Phone: 408-522-0449, Fax: 408-522-3839, E-mail: dmaciel@teledyne.com

DSCC Contact: Mr. Edward Raybould, Phone: 614-692-0582, Fax: 614-692-6942, E-mail: vqh.esr@dla.mil

Quality Management (QM) Program: TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: RF Cascadable Amplifier, Microwave Cascadable Amplifier, Mixers, Attenuators, Limiters, Switches, Multi-function

Qualification Letters: VQ(VQH-00-0037), VQ(VQH-01-0128)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Thin Film

Assembly Information: See Note 1/

Assembly Flows: 351393

Substrate Attach: Solder

Element Attach: Conductive Epoxy, Nonconductive Epoxy, Solder

Add-on Elements: Unpackaged Die, Chip Capacitors, Inductors

Wire Bonding: Gold, Copper

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, TO Can, Projection Weld, 1.37 Inch Seal Perimeter, 4 Leads, Gold Lead Finish; Metal Package, Flatpack, Seam Weld, 2.13 Inch Seal Perimeter, 4 Leads, Gold Lead Finish; Metal/Ceramic Package, SMT0, Seam Weld, 2.13 Inch Seal Perimeter, 4 Leads, Gold Lead Finish

Sourcing and Qualification Unit, Hybrid Devices Team, DSCC-VQH

DLA Land and Maritime - VQ

MIL-PRF-38534 QML Program Status

VPT Inc/Delta Electronics (CAGE Code: 0ZBZ6)

1971 Kraft Dr Ste 1000, Blacksburg, VA 24060, US

Company Contact: Mr. Shawn Graham, Phone: 540-552-5000 x7566, Fax: 540-552-5003, E-mail: sgraham@vptpower.com

DSCC Contact: Ms. Binh Tonnu, Phone: 614-692-0586, Fax: 614-692-6942, E-mail: vqh.bt@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 1

Approved ISO 9000 System: No

Technologies: DC/DC Converters, Filters

Delta Electronics, Inc Taoyuan Shien, Taiwan Plant

Qualification Letters: VQ(VQH-03-3408), VQ(VQH-05-007383), VQ(VQH-06-009911), VQ(VQH-06-010083), VQ(VQH-06-010462), VQ(VQH-06-010463), VQ(VQH-06-010748), VQ(VQH-07-012667), VQ(VQH-08-014580), VQ(VQH-09-017993), VQ(VQH-09-017994), VQ(VQH-11-022477), VQ(VQH-11-022562), VQ(VQH-12-024201), VQ(VQH-12-024839), VQ(VQH-13-025426), VQ(VQH-13-025533), VQ(VQH-13-025534), VQ(VQH-13-025667), VQ(VQH-13-025769), VQ(VQH-13-025866), VQ(VQH-13-025867), VQ(VQH-13-026652), VQ(VQH-13-026658)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: MFG-001

Substrate Fabrication: Thick Film on Alumina, 4 Conductor Level(s), Resistors; Thick Film on Alumina, 1 Conductor Level(s), Resistors; Thick Film on Alumina, 4 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: MFG-001

Substrate Attach: Solder

Element Attach: Conductive Epoxy, Solder, Nonconductive Epoxy, RTV

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors, Magnetics, Bonding Chip, Copper Straps, Flexible Circuits, Wirewound Resistor

Wire Bonding: Aluminum, Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Dual-in-line, Projection Weld, 5.14 Inch Seal Perimeter, 9 Leads, Gold Lead Finish; Metal Package, Dual-in-line, Bathtub, Seam Weld, 6.44 Inch Seal Perimeter, 10 Leads, Gold Lead Finish; Metal Package, Peripheal Leads, Bathtub, Seam Weld, 8.00 Inch Seal Perimeter, 12 Leads, Gold Lead Finish

Standardized Microcircuit Drawing (SMD) Approved Sources are available at the following web pages:

Qualification Part Search: <http://www.landandmaritime.dla.mil/programs/psearch/>

Standard Microcircuit Cross-Reference: <http://www.landandmaritime.dla.mil/Programs/Smcr/>

Qualified Products Database: <http://qpldocs.dla.mil/search/parts.aspx?qpl=1116>